

MEMS ENCLOSURE

ABSTRACT OF THE DISCLOSURE

A low-cost, high-performance, reliable micromirror package (300) that replaces the ceramic substrate in
5 conventional packages with a printed circuit board
substrate (30) and a molded plastic case (33), and the
cover glass with a window (36), preferably an optically
clear plastic window. The printed circuit board
substrate (30) allows for either external bond pads or
10 flex cable connection of the micromirror package to the
projector's motherboard. These packages support flexible
snap-in, screw-in, ultrasonic plastic welding, or
adhesive welding processes to overcome the high cost seam
welding process of many conventional packages.